



# ThunderClad 2A

Core: TU-883A

Prepreg: TU-883P A

ThunderClad 2A ( TU-883A ) is a very low loss category material based on a high performance modified FR-4 resin. This material is reinforced with regular woven E-glass and designed with very low dielectric constant and dissipation factor resin system for high speed low loss, radio frequency and wireless applications. ThunderClad 2A material is suitable for environmental protection lead free process and also compatible with FR-4 processes. ThunderClad 2A laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability and CAF resistance.

## Applications

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

## Performance and Processing Advantages

- Excellent electrical properties & MOT level
- Dielectric constant is 3.44 @ 10GHz
- Dissipation factor is 0.0032 @ 10GHz
- Stable and flat Dk/Df performance over frequency and temperature
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Anti-CAF capability
- Excellent through-hole and soldering reliability
- Halogen Free

## Industry Approvals

- IPC-4101E Specification Number: /134
- IPC-4101E/134 Validation Services QPL Certified
- UL File Number : E1 89572
- ANSI Grade : No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 160°C

## Standard Availability

- Thickness: 0.002"[0.05mm] to 0.030" [0.76mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 2 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 106, 1078, 3313, 2116 and other prepreg grades are available upon request





Typical Properties		
	Typical Values	Test Condition
<b>Thermal</b>		
Tg (DMA) Tg (TMA) Td (TGA)	240 °C 200 °C 430 °C	E-2/105+des
CTE x/y axis CTE z-axis α1 CTE z-axis α2 CTE z-axis	12/13 ppm/°C 35 ppm/°C 200 ppm/°C 2.0 %	Ambient to Tg Pre-Tg Post-Tg 50 to 260°C
Thermal Stress, Solder Float, 288°C	> 60 sec	A
T-260 T-288 T-300	> 60 min > 60 min > 60 min	E-2/105+des
Flammability	94V-0	E-24/125+des
<b>Electrical</b>		
Permittivity (RC70%) 10GHz (SPC method) Impedance simulation DK	3.44 2.92	E-2/105
Loss Tangent (RC70%) 10GHz (SPC method)	0.0032	E-2/105
Volume Resistivity	> 10 <sup>10</sup> MΩ·cm	C-96/35/90
Surface Resistivity	> 10 <sup>8</sup> MΩ	C-96/35/90
Electric Strength	> 40 KV/mm	-
Dielectric Breakdown Voltage	> 50 KV	-
<b>Mechanical</b>		
Young's Modulus Warp Direction Fill Direction	31 GPa 29 GPa	A
Flexural Strength Lengthwise Crosswise	> 60,000 psi > 50,000 psi	A A
Peel Strength, 1.0 oz. HVLP Cu foil	4~6 lb/in	A
Water Absorption	0.08 %	E-1/105+des+D-24/23

NOTE:

1. Property values are for information purposes only and not intended for specification.
2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
3. This product is based on a patent pending technology.

